

Stereo Audio Volume Control

FEATURES

- **DIGITALLY-CONTROLLED ANALOG VOLUME CONTROL**
Two Independent Audio Channels
Serial Control Interface
Zero Crossing Detection
Mute Function
- **WIDE GAIN AND ATTENUATION RANGE**
+31.5dB to -95.5dB with 0.5dB Steps
- **LOW NOISE AND DISTORTION**
120dB Dynamic Range
0.0004% THD+N at 1kHz (U-Grade)
0.0002% THD+N at 1kHz (A-Grade)
- **NOISE-FREE LEVEL TRANSITIONS**
- **LOW INTERCHANNEL CROSSTALK**
-130dBFS
- **POWER SUPPLIES: $\pm 5V$ Analog, +5V Digital**
- **AVAILABLE IN DIP-16 AND SOL-16 PACKAGES**
- **PIN AND SOFTWARE COMPATIBLE WITH THE CRYSTAL CS3310**

APPLICATIONS

- **AUDIO AMPLIFIERS**
- **MIXING CONSOLES**
- **MULTI-TRACK RECORDERS**
- **BROADCAST STUDIO EQUIPMENT**
- **MUSICAL INSTRUMENTS**
- **EFFECTS PROCESSORS**
- **A/V RECEIVERS**
- **CAR AUDIO SYSTEMS**

DESCRIPTION

The PGA2311 is a high-performance, stereo audio volume control designed for professional and high-end consumer audio systems. Using high performance operational amplifier stages internal to the PGA2311 yields low noise and distortion, while providing the capability to drive 600 Ω loads directly without buffering. The 3-wire serial control interface allows for connection to a wide variety of host controllers, in addition to support for daisy-chaining of multiple PGA2311 devices.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V_{A+}	+5.5V
V_{A-}	-5.5V
V_{D+}	+5.5V
V_{A+} to V_{D+}	$< \pm 0.3V$
Analog Input Voltage	0V to V_{A+} , V_{A-}
Digital Input Voltage	-0.3V to V_{D+}
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Package Temperature (IR reflow, 10s)	+235°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability.



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	OPERATING TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
PGA2311 (U-Grade)	DIP-16	N	-40°C to +85°C	PGA2311P	PGA2311P	Rails
	SOL-16	DW		PGA2311U	PGA2311U	Rails
				PGA2311U	PGA2311U/1K	Tape and Reel, 1000
PGA2311 (A-Grade)	DIP-16	N	-40°C to +85°C	PGA2311PA	PGA2311PA	Rails
	SOL-16	DW		PGA2311UA	PGA2311UA	Rails
				PGA2311UA	PGA2311UA/1K	Tape and Reel, 1000

(1) For the most current specifications and package information, refer to our web site at www.ti.com.

ELECTRICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_{A+} = +5V$, $V_{A-} = -5V$, $V_{D+} = +5V$, $R_L = 100k\Omega$, $C_L = 20pF$, BW measure = 10Hz to 20kHz, unless otherwise noted.

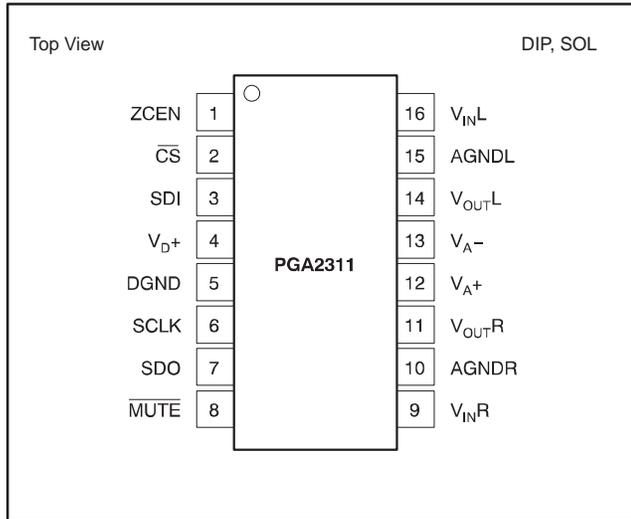
PARAMETER	CONDITIONS	PGA2311P, U (U-Grade)			PGA2311PA, UA (A-Grade)			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
DC CHARACTERISTICS								
Step Size	Gain Setting = 31.5dB		0.5			0.5		dB
Gain Error			± 0.05			± 0.05		dB
Gain Matching				± 0.05			± 0.05	dB
Input Resistance				10			10	k Ω
Input Capacitance			3			3	pF	
AC CHARACTERISTICS								
THD+N	$V_{IN} = 2V_{rms}$, $f = 1kHz$ $V_{IN} = AGND$, Gain = 0dB		0.0004	0.001		0.0002	0.0004	%
Dynamic Range			116	120		116	120	
Voltage Range, Output		$(V_{A-}) + 1.25$		$(V_{A+}) - 1.25$	$(V_{A-}) + 1.25$		$(V_{A+}) - 1.25$	V
Voltage Range, Input (without clipping)			2.5			2.5		V _{rms}
Output Noise	$V_{IN} = AGND$, Gain = 0dB $f = 1kHz$		2.5	4		2.5	4	μV_{rms}
Interchannel Crosstalk				-130			-130	
OUTPUT BUFFER								
Offset Voltage	$V_{IN} = AGND$, Gain = 0dB		0.25	0.5		0.25	0.5	mV
Load Capacitance Stability			100			100		pF
Short-Circuit Current				50			50	mA
Unity-Gain Bandwidth, Small Signal				10			10	MHz

ELECTRICAL CHARACTERISTICS (Cont.)

 At $T_A = +25^\circ\text{C}$, $V_{A+} = +5\text{V}$, $V_{A-} = -5\text{V}$, $V_{D+} = +5\text{V}$, $R_L = 100\text{k}\Omega$, $C_L = 20\text{pF}$, BW measure = 10Hz to 20kHz, unless otherwise noted.

PARAMETER	CONDITIONS	PGA2311P, U (U-Grade)			PGA2311PA, UA (A-Grade)			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
DIGITAL CHARACTERISTICS								
High-Level Input Voltage, V_{IH}	$I_O = 200\mu\text{A}$	+2.0		V_{D+}	+2.0		V_{D+}	V
Low-Level Input Voltage, V_{IL}		-0.3		0.8	-0.3		0.8	V
High-Level Output Voltage, V_{OH}		$(V_{A+}) - 1.0$			$(V_{D+}) - 1.0$			V
Low-Level Output Voltage, V_{OL}		$I_O = -3.2\text{mA}$		0.4			0.4	V
Input Leakage Current				1	10		1	10
SWITCHING CHARACTERISTICS								
Serial Clock (SCLK) Frequency	f_{SCLK}	0		6.25	0		6.25	MHz
Serial Clock (SCLK) Pulse Width LOW	t_{PH}	80			80			ns
Serial Clock (SCLK) Pulse Width HIGH	t_{PL}	80			80			ns
MUTE Pulse Width LOW	t_{MI}	2.0			2.0			ms
Input Timing								
SDI Setup Time	t_{SDS}	20			20			ns
SDI Hold Time	t_{SDH}	20			20			ns
$\overline{\text{CS}}$ Falling to SCLK Rising	t_{CSCR}	90			90			ns
SCLK Falling to $\overline{\text{CS}}$ Rising	t_{CFCS}	35			35			ns
Output Timing								
$\overline{\text{CS}}$ LOW to SDO Active	t_{CSO}			35			35	ns
SCLK Falling to SDO Data Valid	t_{CFDO}			60			60	ns
$\overline{\text{CS}}$ HIGH to SDO High Impedance	t_{CSZ}			100			100	ns
POWER SUPPLY								
Operating Voltage								
V_{A+}		+4.75	+5	+5.25	+4.75	+5	+5.25	V
V_{A-}		-4.75	-5	-5.25	-4.75	-5	-5.25	V
V_{D+}		+4.75	+5	+5.25	+4.75	+5	+5.25	V
Quiescent Current								
I_{A+}	$V_{A+} = +5\text{V}$		8	10		8	10	mA
I_{A-}	$V_{A-} = -5\text{V}$		10	12		10	12	mA
I_{D+}	$V_{D+} = +5\text{V}$		0.5	1.0		0.5	1.0	mA
Power-Supply Rejection Ratio PSRR (250Hz)			100			100		dB
TEMPERATURE RANGE								
Operating Range		-40		+85	-40		+85	$^\circ\text{C}$
Storage Range		-65		+150	-65		+150	$^\circ\text{C}$
Thermal Resistance, θ_{JC}								
DIP-16			60			60		$^\circ\text{C}/\text{W}$
SOL-16			50			50		$^\circ\text{C}/\text{W}$

PIN CONFIGURATION

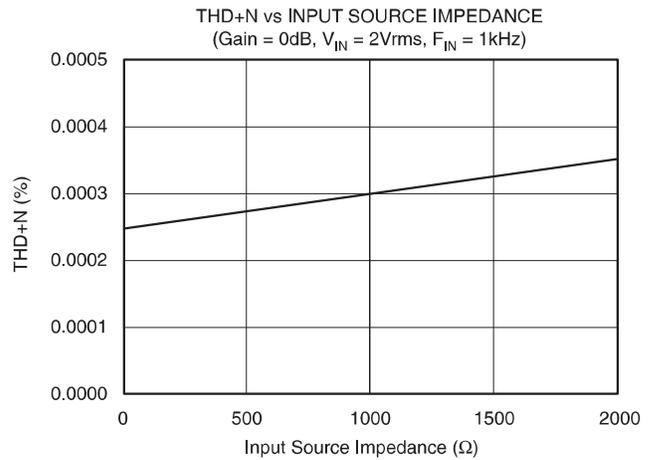
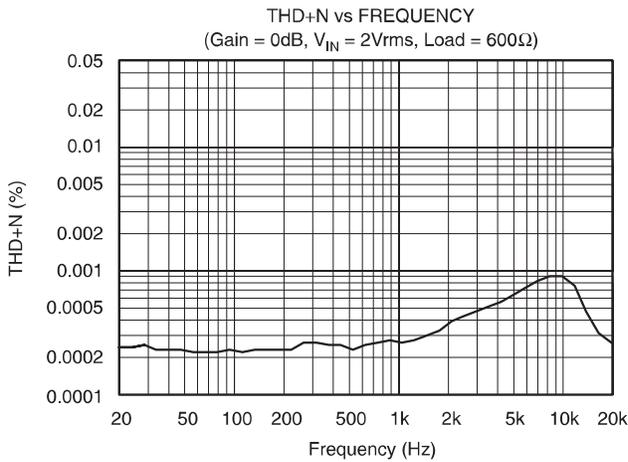
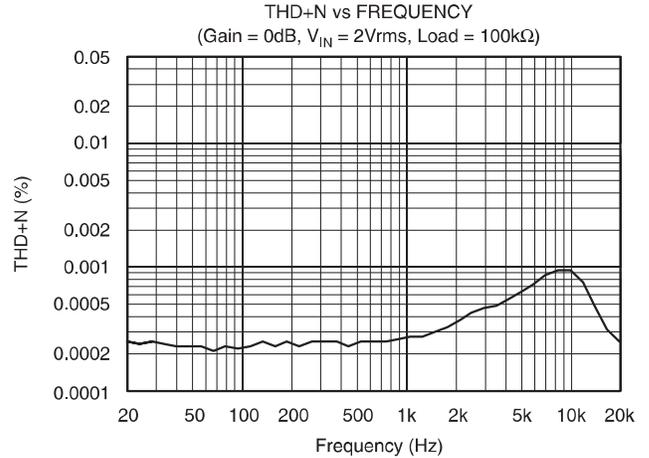
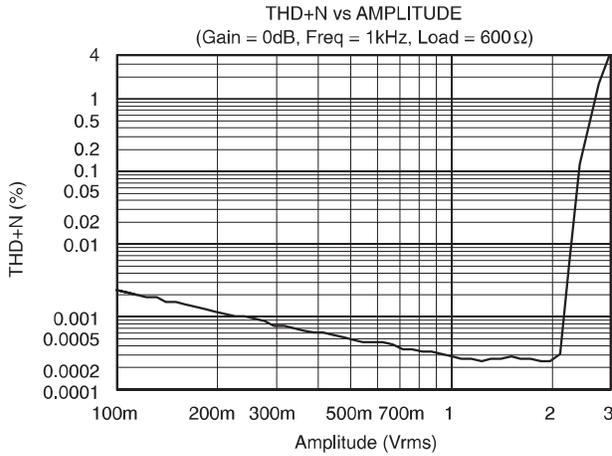
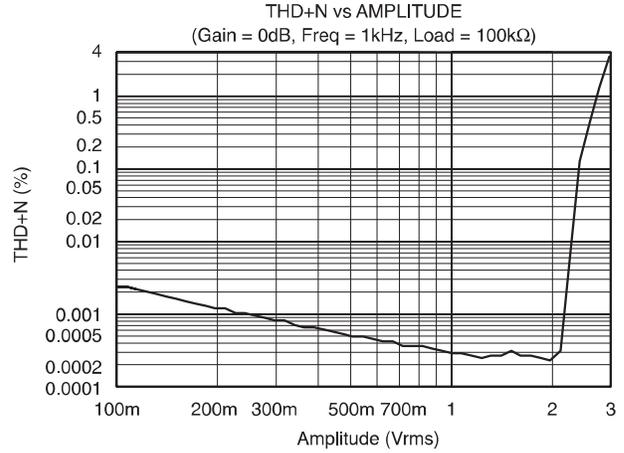
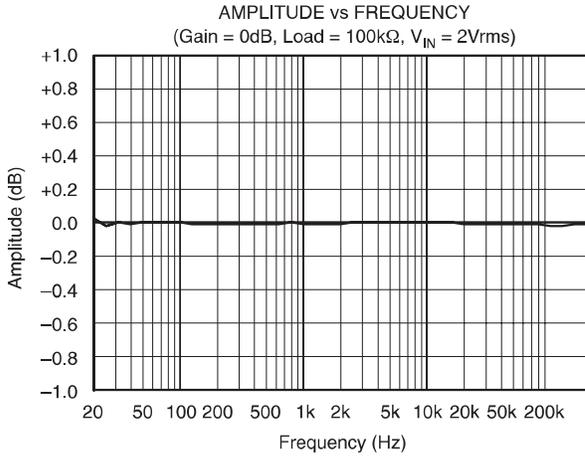


PIN ASSIGNMENTS

PIN	NAME	FUNCTION
1	ZCEN	Zero Crossing Enable Input (Active HIGH)
2	$\overline{\text{CS}}$	Chip Select Input (Active LOW)
3	SDI	Serial Data input
4	V_{D+}	Digital Power Supply, +5V
5	DGND	Digital Ground
6	SCLK	Serial Clock Input
7	$\overline{\text{SDO}}$	Serial Data Output
8	$\overline{\text{MUTE}}$	Mute Control Input (Active LOW)
9	V_{INR}	Analog Input, Right Channel
10	AGNDR	Analog Ground, Right Channel
11	V_{OUTR}	Analog Output, Right Channel
12	V_{A+}	Analog Power Supply, +5V
13	V_{A-}	Analog Power Supply, -5V
14	V_{OUTL}	Analog Output, Left Channel
15	AGNDL	Analog Ground, Left Channel
16	V_{INL}	Analog Input, Left Channel

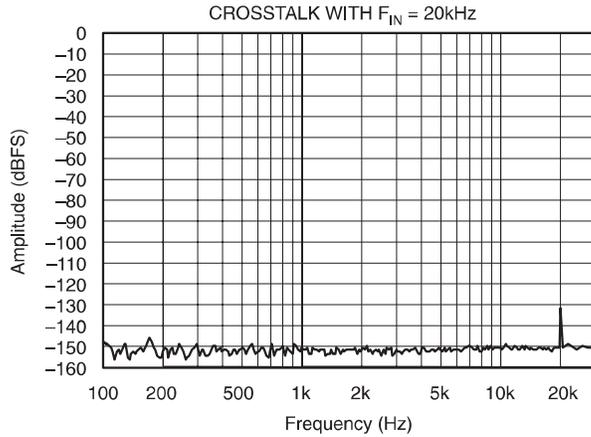
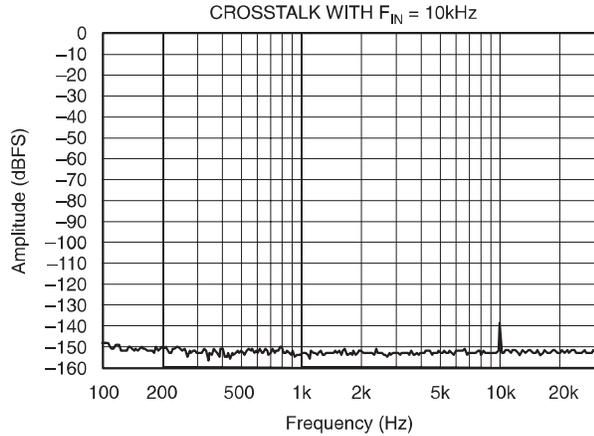
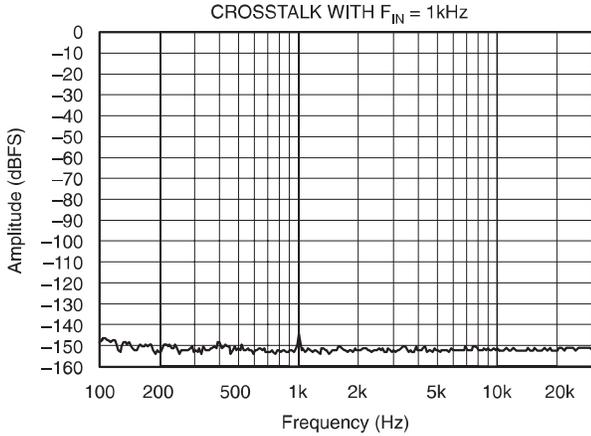
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_{A+} = +5\text{V}$, $V_{A-} = -5\text{V}$, $V_{D+} = +5\text{V}$, $R_L = 100\text{k}\Omega$, $C_L = 20\text{pF}$, BW measure = 10Hz to 20kHz, unless otherwise noted.
 (NOTE: All plots taken with PGA2311 A-Grade.)



TYPICAL CHARACTERISTICS (CONT.)

At $T_A = +25^\circ\text{C}$, $V_{A+} = +5\text{V}$, $V_{A-} = -5\text{V}$, $V_{D+} = +5\text{V}$, $R_L = 100\text{k}\Omega$, $C_L = 20\text{pF}$, BW measure = 10Hz to 20kHz, unless otherwise noted.
(NOTE: All plots taken with PGA2311 A-Grade.)



GENERAL DESCRIPTION

The PGA2311 is a stereo audio volume control. It may be used in a wide array of professional and consumer audio equipment. The PGA2311 is fabricated in a sub-micron CMOS process.

The heart of the PGA2311 is a resistor network, an analog switch array, and a high-performance op amp stage. The switches are used to select taps in the resistor network that, in turn, determine the gain of the amplifier stage. Switch selections are programmed using a serial control port. The serial port allows connection to a wide variety of host controllers. Figure 1 shows a functional block diagram of the PGA2311.

POWER-UP STATE

On power up, "power-up reset" is activated for about 100ms during which the circuit is in hardware MUTE state and all internal flip-flops are reset. At the end of this period, the offset calibration is initiated without any external signals. Once this has been completed, the gain byte value for both the left and right channels are set to 00_{HEX}, or the software MUTE condition. The gain will remain at this setting until the host controller programs new settings for for each channel via the serial control port.

If during normal operation the power supply voltage drops below $\pm 3.2\text{V}$, the circuit enters a hardware MUTE state. A power-up sequence will be initiated if the power supply voltage returns to greater than $\pm 3.2\text{V}$.

ANALOG INPUTS AND OUTPUTS

The PGA2311 includes two independent channels, referred to as the left and right channels. Each channel has a corresponding input and output pin. The input and output pins are unbalanced, or referenced to analog ground (either AGNDR or AGNDL). The inputs are named V_{INR} (pin 9) and V_{INL} (pin 16), while the outputs are named V_{OUTR} (pin 11) and V_{OUTL} (pin 14).

The input and output pins may swing within 1.25V of the analog power supplies, V_{A+} (pin 12) and V_{A-} (pin 13). Given $V_{A+} = +5\text{V}$ and $V_{A-} = -5\text{V}$, the maximum input or output voltage range is 7.5Vp-p.

For optimal performance, it is best to drive the PGA2311 with a low source impedance. A source impedance of 600 Ω or less is recommended. Source impedances up to 2k Ω will cause minimal degradation of THD+N. Please refer to the "THD+N vs Source Impedance" plot in the Typical Characteristics section of the datasheet.

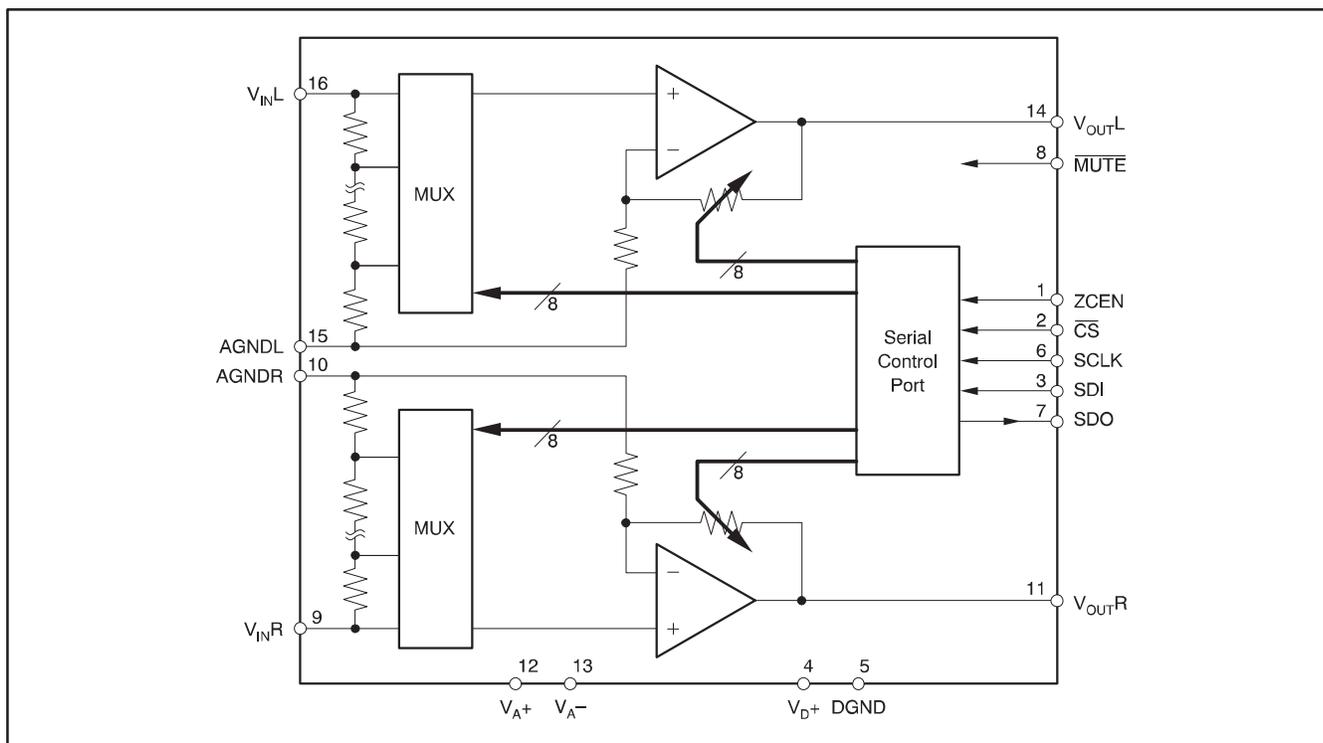


Figure 1. PGA2311 Block Diagram.

SERIAL CONTROL PORT

The serial control port is utilized to program the gain settings for the PGA2311. The serial control port includes three input pins and one output pin. The inputs include \overline{CS} (pin 2), SDI (pin 3), and SCLK (pin 6). The sole output pin is SDO (pin 7).

The \overline{CS} pin functions as the chip select input. Data may be written to the PGA2311 only when \overline{CS} is LOW. SDI is the serial data input pin. Control data is provided as a 16-bit word at the SDI pin, 8 bits each for the left and right channel gain settings.

Data is formatted as MSB first, straight binary code. SCLK is the serial clock input. Data is clocked into SDI on the rising edge of SCLK.

SDO is the serial data output pin, and is used when daisy-chaining multiple PGA2311 devices. Daisy-chain operation is described in detail later in this section. SDO is a tri-state output, and assumes a high impedance state when \overline{CS} is HIGH.

The protocol for the serial control port is shown in Figure 2. See Figure 3 for detailed timing specifications for the serial control port.

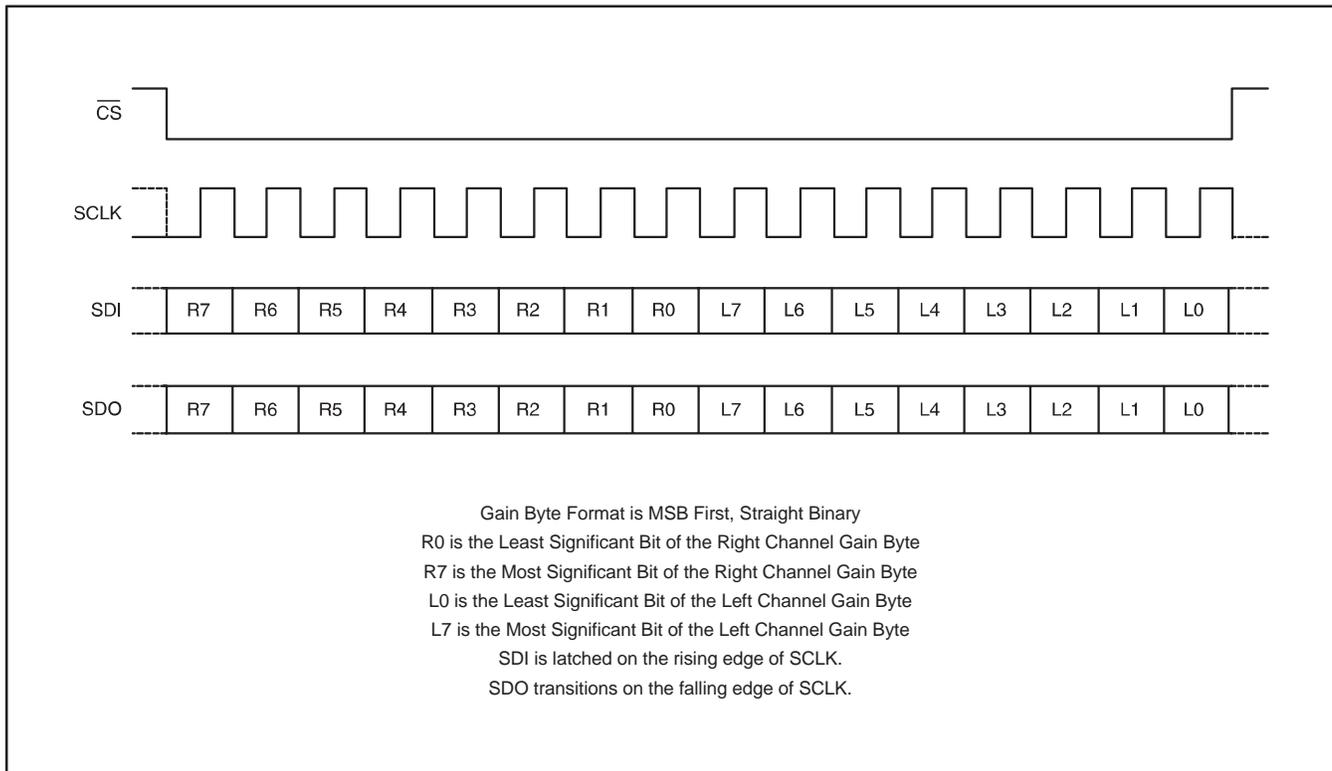


Figure 2. Serial Interface Protocol.

GAIN SETTINGS

The gain for each channel is set by its corresponding 8-bit code, either R[7:0] or L[7:0] (see Figure 2). The gain code data is straight binary format. If we let N equal the decimal equivalent of R[7:0] or L[7:0], then the following relationships exist for the gain settings:

For N = 0:

Mute Condition. The input multiplexer is connected to analog ground (AGNDR or AGNDL).

For N = 1 to 255:

$$\text{Gain (dB)} = 31.5 - [0.5 w (255 - N)]$$

This results in a gain range of +31.5dB (with N = 255) to -95.5dB (with N = 1).

Changes in gain setting may be made with or without zero crossing detection. The operation of the zero crossing detector and timeout circuitry is discussed later in this data sheet.

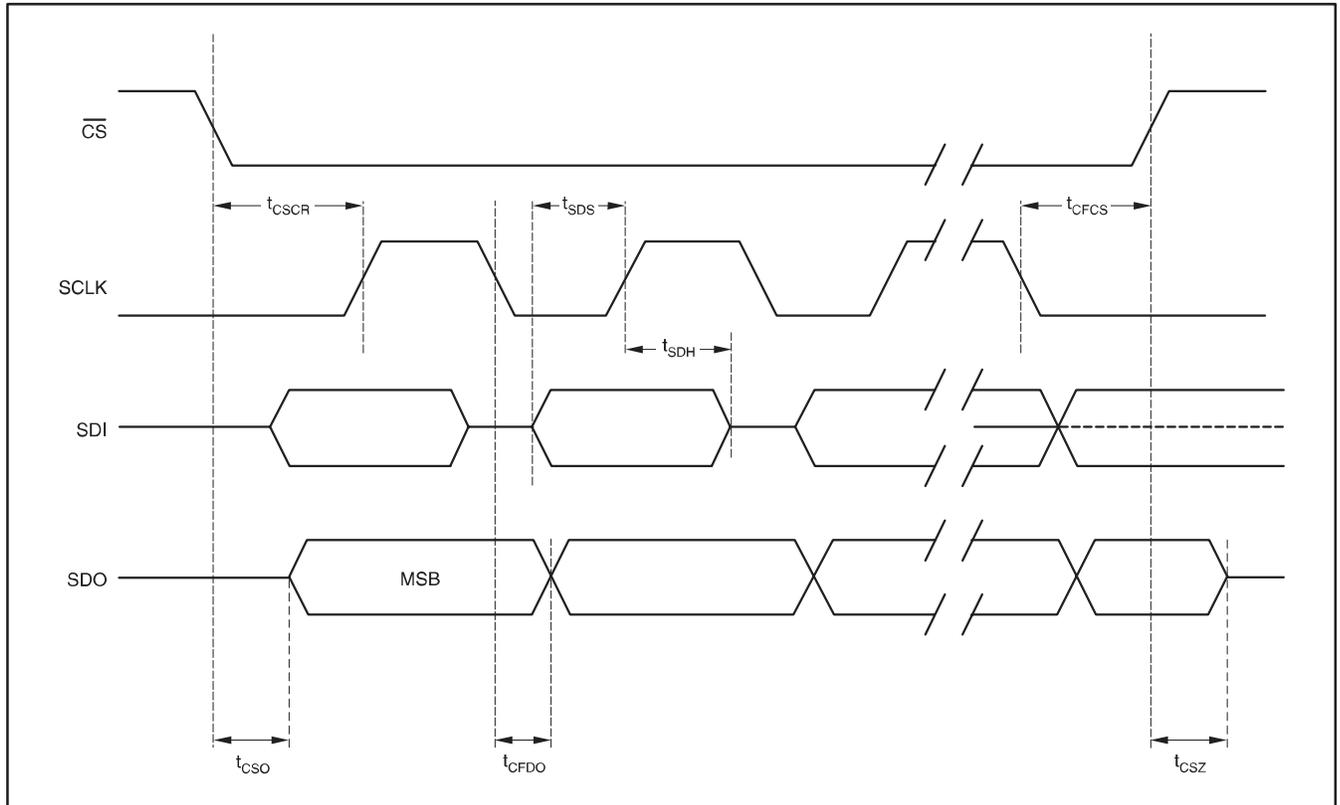


Figure 3. Serial Interface Timing Requirements.

DAISY-CHAINING MULTIPLE PGA2311 DEVICES

In order to reduce the number of control signals required to support multiple PGA2311 devices on a printed circuit board, the serial control port supports daisy-chaining of multiple PGA2311 devices. Figure 4 shows the connection requirements for daisy-chain operation. This arrangement allows a 3-wire serial interface to control many PGA2311 devices.

As shown in Figure 4, the SDO pin from device #1 is connected to the SDI input of device #2, and is repeated for additional devices. This in turn forms a large shift register, in which gain data may be written for all PGA2311s connected to the serial bus. The length of the shift register is $16 \cdot N$ bits, where N is equal to the number of PGA2311 devices included in the chain. The \overline{CS} input must remain LOW for $16 \cdot N$ SCLK periods, where N is the number of devices connected in the chain, in order to allow enough SCLK cycles to load all devices.

ZERO CROSSING DETECTION

The PGA2311 includes a zero crossing detection function that can provide for noise-free level transitions. The concept is to change gain settings on a zero crossing of the input signal, thus minimizing audible glitches. This function is enabled or disabled using the ZCEN input (pin 1). When ZCEN is LOW, zero crossing detection is disabled. When ZCEN is HIGH, zero crossing detection will be enabled.

The zero crossing detection takes effect with a change in gain setting for a corresponding channel. The new gain setting will not be implemented until either positive slope zero crossing is detected or a time-out period of 16ms has elapsed. In the case of a time-out, the new gain setting takes effect with no attempt to minimize audible artifacts.

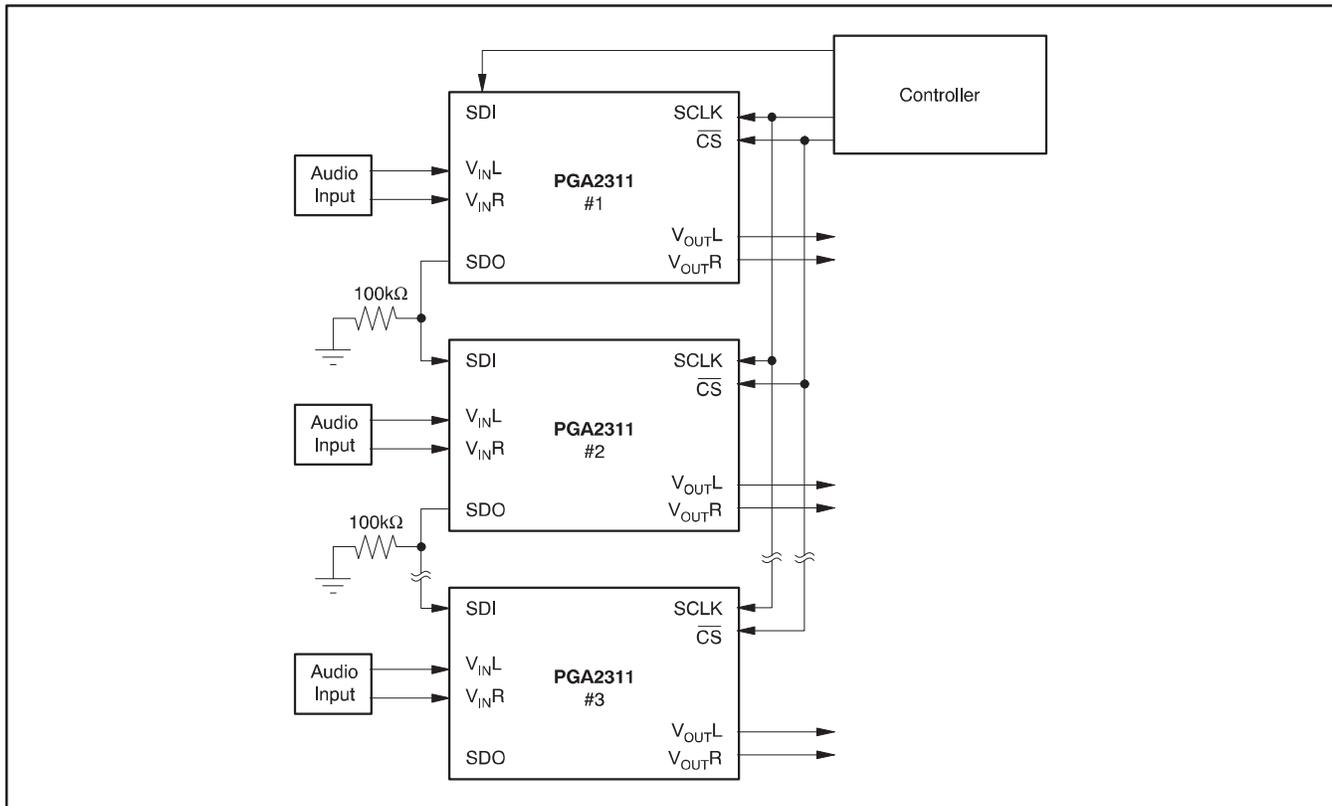


Figure 4. Daisy-Chaining Multiple PGA2311 Devices.

PRINTED CIRCUIT BOARD (PCB) LAYOUT GUIDELINES

It is recommended that the ground planes for the digital and analog sections of the PCB be separate from one another. The planes should be connected at a single point. Figure 6 shows the recommended PCB floor plan for the PGA2311.

The PGA2311 is mounted so that it straddles the split between the digital and analog ground planes. Pins 1 through 8 are oriented to the digital side of the board, while pins 9 through 16 are on the analog side of the board.

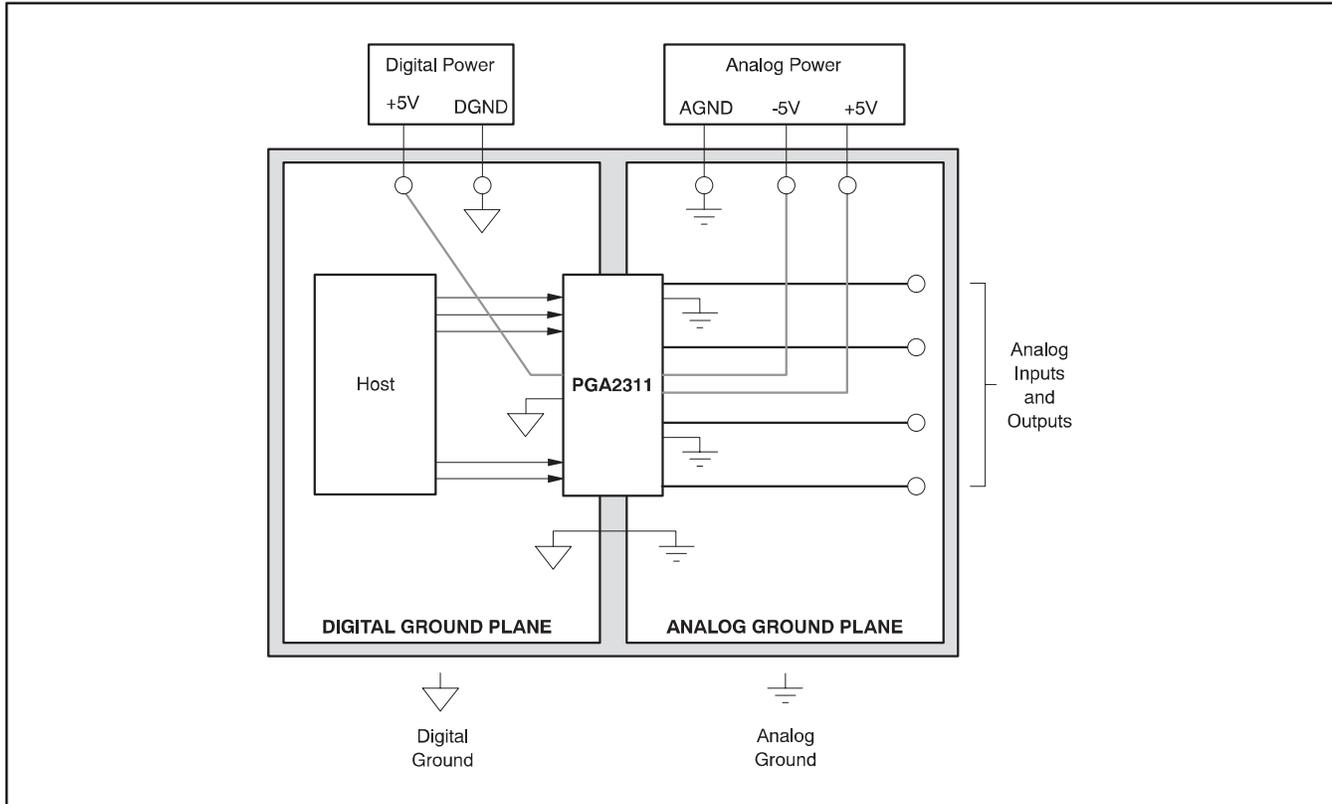


Figure 6. Typical PCB Layout Floor Plan.

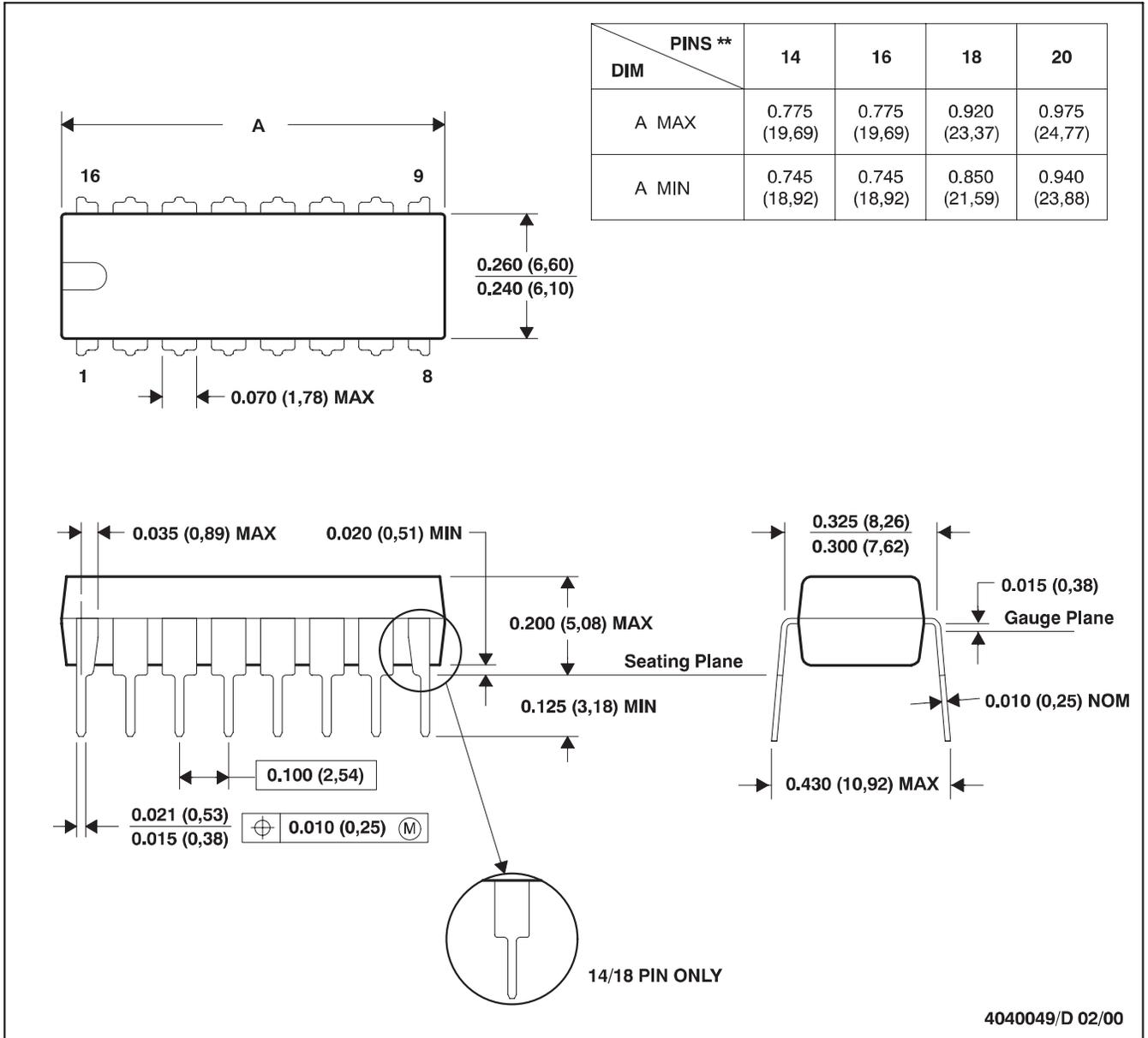
PACKAGE DRAWINGS

MPDI002B ± JANUARY 1995 ± REVISED FEBRUARY 2000

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/D 02/00

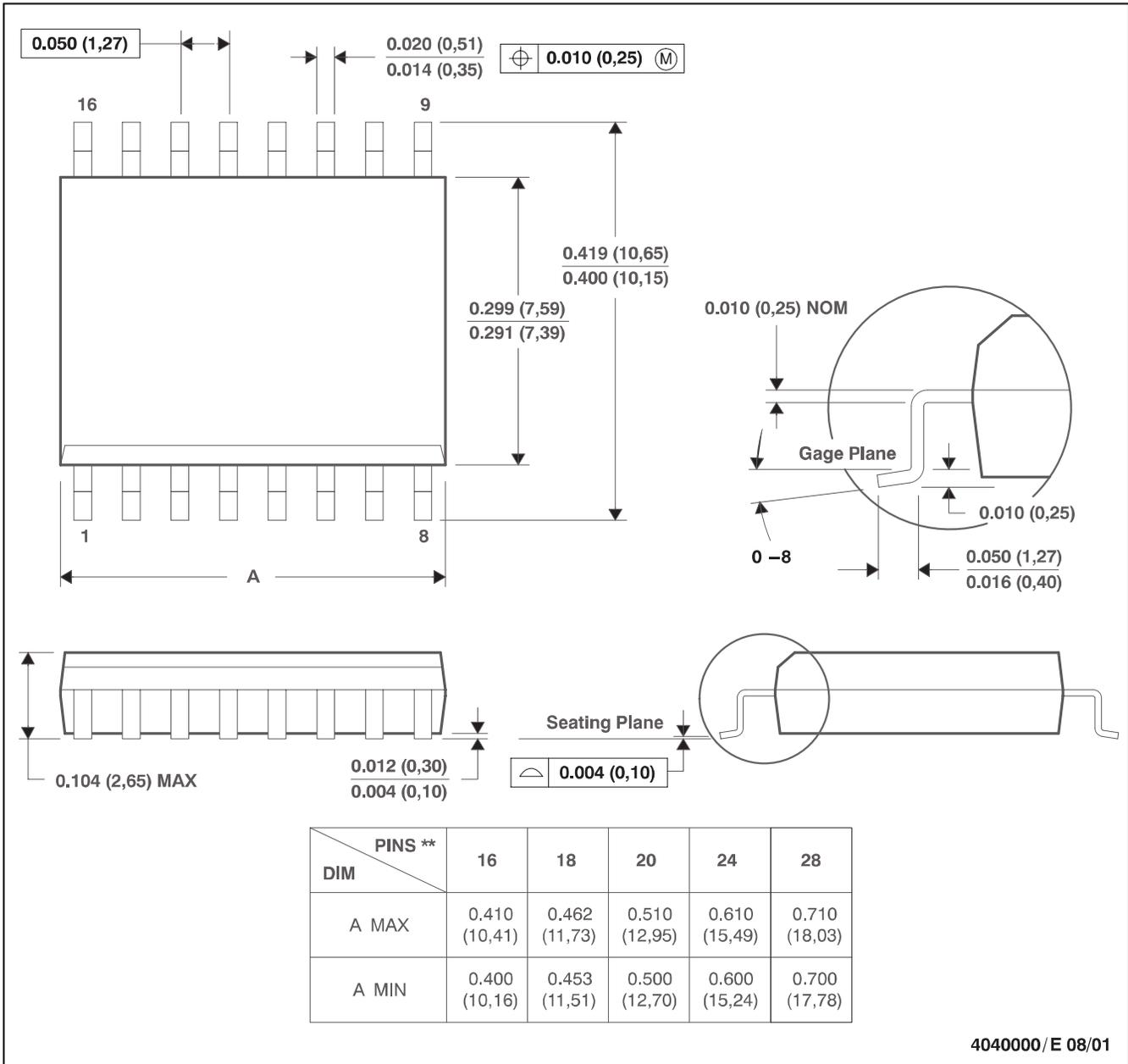
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001).

PACKAGE DRAWINGS (Cont.)

DW (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



4040000/E 08/01

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
PGA2311P	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
PGA2311PA	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
PGA2311PAG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
PGA2311PG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
PGA2311U	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311U/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311U/1KG4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311UA	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311UA/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311UA/1KG4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311UAG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
PGA2311UG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

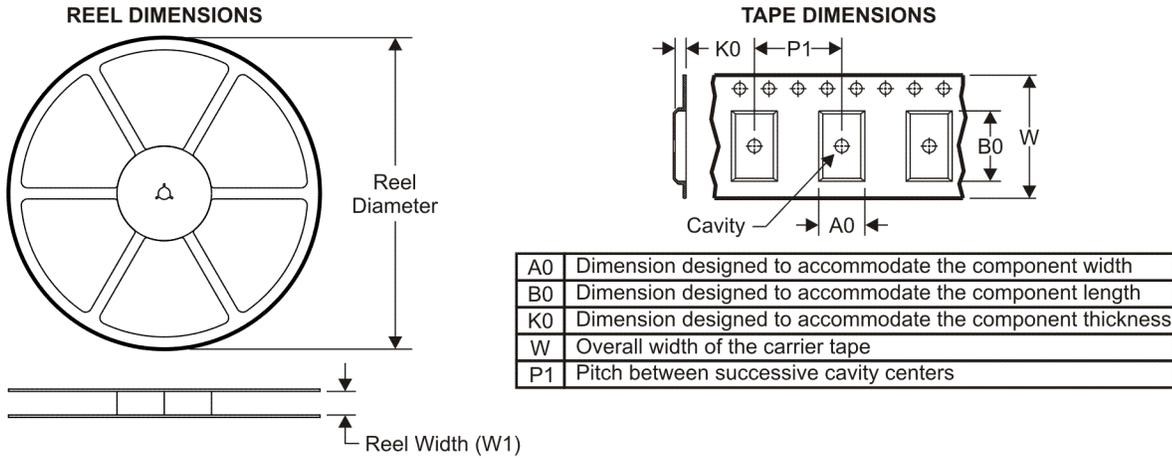
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

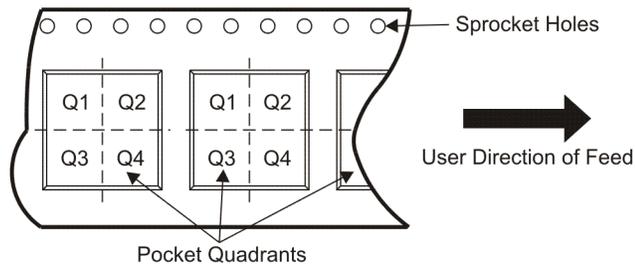
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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



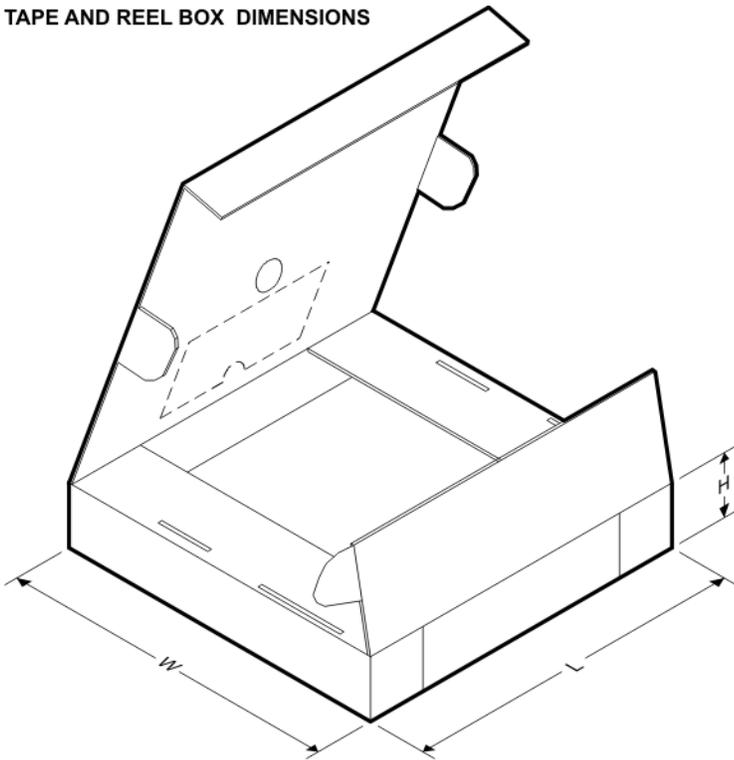
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PGA2311U/1K	SOIC	DW	16	1000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1
PGA2311UA/1K	SOIC	DW	16	1000	330.0	16.4	10.85	10.8	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PGA2311U/1K	SOIC	DW	16	1000	346.0	346.0	33.0
PGA2311UA/1K	SOIC	DW	16	1000	346.0	346.0	33.0

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